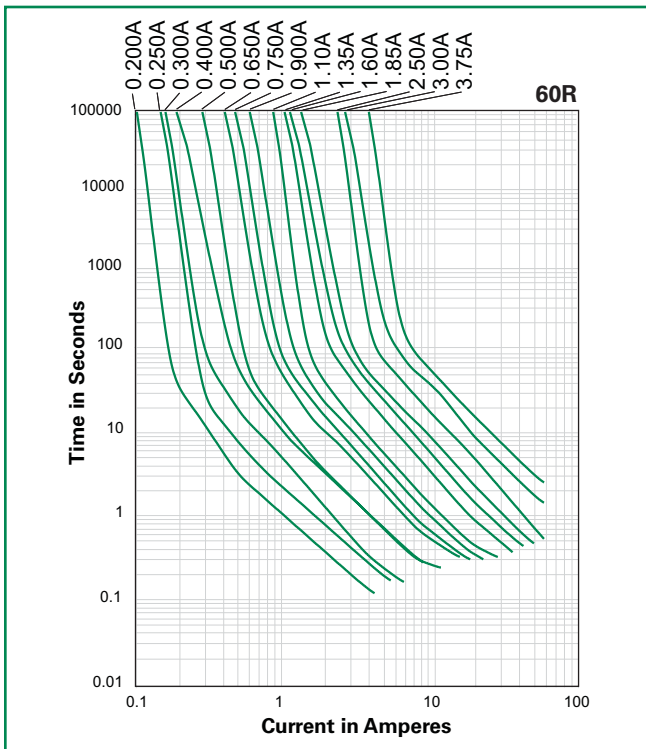


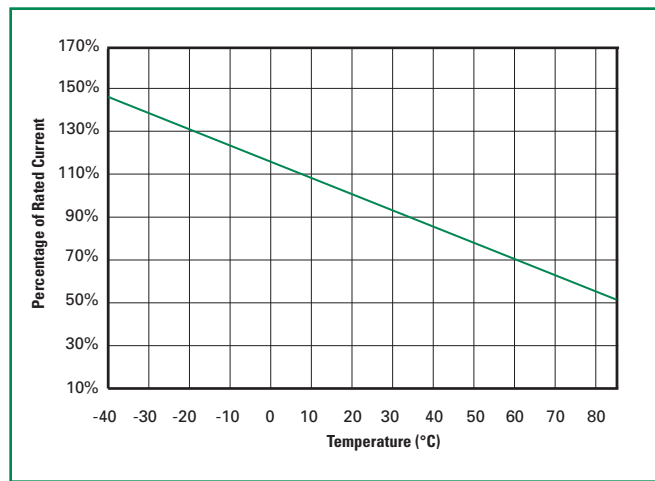
Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
	Hold Current (A)								
60R010	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.04
60R020	0.31	0.27	0.24	0.20	0.16	0.14	0.13	0.11	0.08
60R025	0.39	0.34	0.30	0.25	0.20	0.18	0.16	0.14	0.10
60R030	0.47	0.41	0.36	0.30	0.24	0.22	0.19	0.16	0.12
60R040	0.62	0.54	0.48	0.40	0.32	0.29	0.25	0.22	0.16
60R050	0.78	0.68	0.60	0.50	0.41	0.36	0.32	0.27	0.20
60R065	1.01	0.88	0.77	0.65	0.53	0.47	0.41	0.35	0.26
60R075	1.16	1.02	0.89	0.75	0.61	0.54	0.47	0.41	0.30
60R090	1.40	1.22	1.07	0.90	0.73	0.65	0.57	0.49	0.36
60R110	1.71	1.50	1.31	1.10	0.89	0.79	0.69	0.59	0.44
60R135	2.09	1.84	1.61	1.35	1.09	0.97	0.85	0.73	0.54
60R160	2.48	2.18	1.90	1.60	1.30	1.15	1.01	0.86	0.64
60R185	2.87	2.52	2.20	1.85	1.50	1.33	1.17	1.00	0.74
60R250	3.88	3.40	2.98	2.50	2.03	1.80	1.58	1.35	1.00
60R300	4.65	4.08	3.57	3.00	2.43	2.16	1.89	1.62	1.20
60R375	5.81	5.10	4.46	3.75	3.04	2.70	2.36	2.03	1.50

Average Time Current Curves



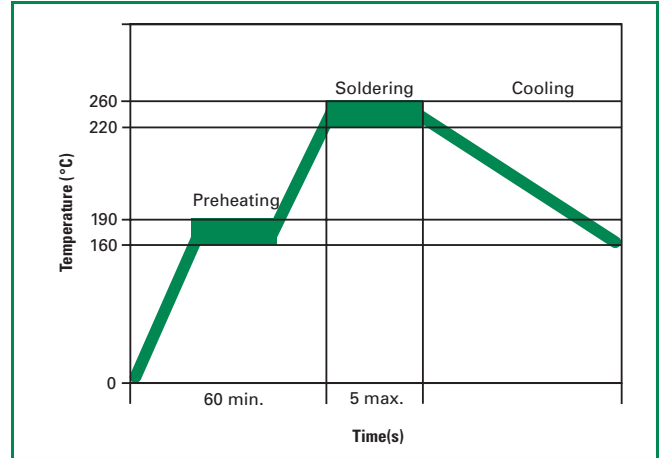
Temperature Derating Curve



The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Soldering Parameters - Wave Soldering

Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer. Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C
Cooling Zone	Cooling by natural convection in air.

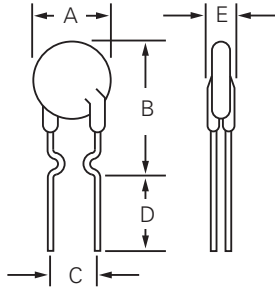

Physical Specifications

Lead Material	.20-.40A: Tin-plated Copper clad steel .50-3.75A: Tin-plated Copper
Soldering Characteristics	Solderability per MIL-STD-202, Method 208E
Insulating Material	Cured, flame retardant epoxy polymer meets UL94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

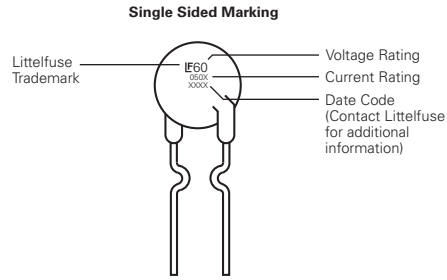
Environmental Specifications

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours /+ 5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 1000 hours /+ 5% typical resistance change
Thermal Shock	+85°C to -40°C 10 times /+ 5% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215F
Moisture Resistance Level	Level 2, J-STD-020C

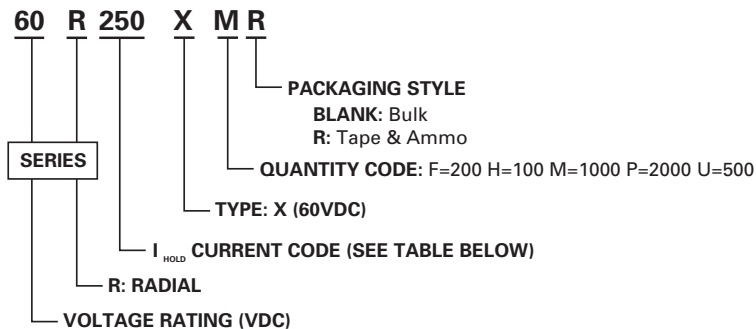
Dimensions



Part Marking System



Part Number	A		B		C		D		E		Physical Characteristics		
	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Lead (dia)		Material
	Max.	Max.	Max.	Max.	Typ.	Typ.	Min.	Min.	Max.	Max.	Inches	mm	
60R010	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/CuFe
60R020	0.29	7.4	0.46	11.7	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/CuFe
60R025	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/CuFe
60R030	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/CuFe
60R040	0.30	7.6	0.53	13.5	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/CuFe
60R050	0.31	7.9	0.54	13.7	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/Cu
60R065	0.37	9.4	0.57	14.5	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/Cu
60R075	0.40	10.2	0.59	15	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/Cu
60R090	0.44	11.2	0.62	15.8	0.20	5.1	0.30	7.6	0.12	3.1	0.02	0.51	Sn/Cu
60R110	0.51	13	0.72	18.2	0.20	5.1	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R135	0.53	13.58	0.78	19.8	0.20	5.1	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R160	0.60	15.36	0.85	21.6	0.20	5.1	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R185	0.66	16.76	0.91	23	0.20	5.1	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R250	0.78	19.93	1.03	26.2	0.40	10.2	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R300	0.91	23.11	1.15	29.3	0.40	10.2	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu
60R375	1.04	26.3	1.22	31.1	0.40	10.2	0.30	7.6	0.12	3.1	0.03	0.81	Sn/Cu

Part Ordering Number System

Packaging

Part Number	Ordering Number	I_{hold} (A)	I_{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
60R010	60R010XU	0.10	010	Bulk	500	U
	60R010XPR			Tape and Ammo	2000	PR
60R020	60R020XU	0.20	020	Bulk	500	U
	60R020XPR			Tape and Ammo	2000	PR
60R025	60R025XU	0.25	025	Bulk	500	U
	60R025XPR			Tape and Ammo	2000	PR
60R030	60R030XU	0.30	030	Bulk	500	U
	60R030XPR			Tape and Ammo	2000	PR
60R040	60R040XU	0.40	040	Bulk	500	U
	60R040XPR			Tape and Ammo	2000	PR
60R050	60R050XU	0.50	050	Bulk	500	U
	60R050XPR			Tape and Ammo	2000	PR
60R065	60R065XU	0.65	065	Bulk	500	U
	60R065XPR			Tape and Ammo	2000	PR
60R075	60R075XU	0.75	075	Bulk	500	U
	60R075XPR			Tape and Ammo	2000	PR
60R090	60R090XU	0.90	090	Bulk	500	U
	60R090XPR			Tape and Ammo	2000	PR
60R110	60R110XU	1.10	110	Bulk	500	U
	60R110XMR			Tape and Ammo	1000	MR
60R135	60R135XF	1.35	135	Bulk	200	F
	60R135XMR			Tape and Ammo	1000	MR
60R160	60R160XF	1.60	160	Bulk	200	F
	60R160XMR			Tape and Ammo	1000	MR
60R185	60R185XF	1.85	185	Bulk	200	F
	60R185XMR			Tape and Ammo	1000	MR
60R250	60R250XF	2.50	250	Bulk	200	F
	60R250XMR			Tape and Ammo	1000	MR
60R300	60R300XF	3.00	300	Bulk	200	F
60R375	60R375XH	3.75	375	Bulk	100	H

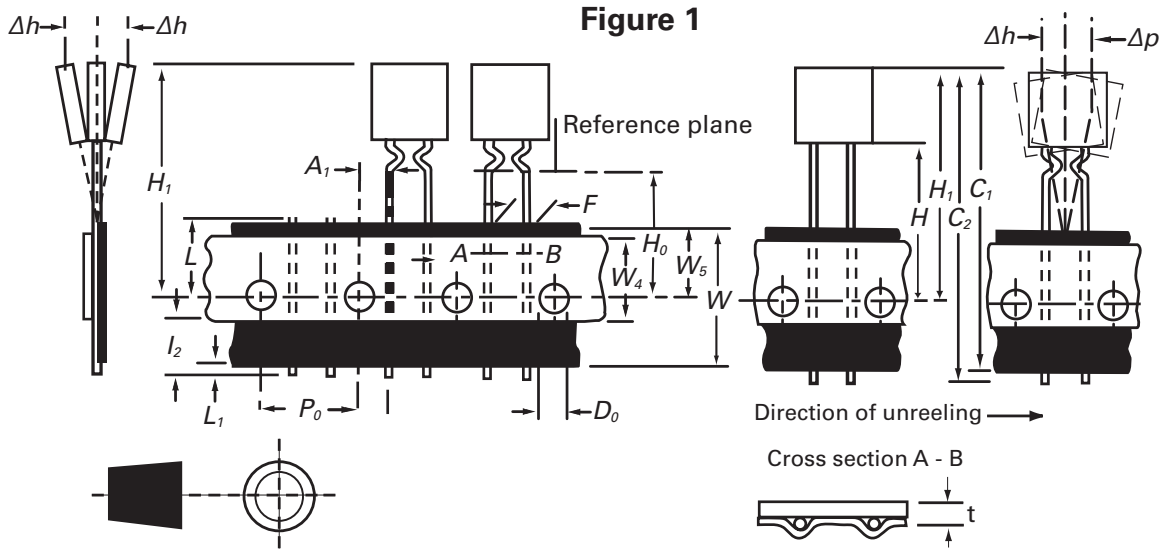
Tape and Ammo Specifications

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension	EIA Mark	IEC Mark	Dimensions	
			Dim. (mm)	Tol. (mm)
Carrier tape width	W	W	18	-0.5 / +1.0
Hold down tape width	W₄	W₀	11	min.
Top distance between tape edges	W₆	W₂	3	max.
Sprocket hole position	W₅	W₁	9	-0.5 / +0.75
Sprocket hole diameter*	D₀	D₀	4	-0.32 / +0.2
Abscissa to plane(straight lead)	H	H	18.5	-/+ 3.0
Abscissa to plane(kinked lead)	H₀	H₀	16	-/+ 0.5
Abscissa to top 60R010-60R090	H₁	H₁	32.2	max.
Abscissa to top 60R110-60R300	H₁		47.5	max.
Overall width without lead protrusion:60R010-60R090	C₁		42.5	max.
Overall width without lead protrusion:60R110-60R300			57	
Overall width with lead protrusion:60R010-60R090	C2		43.2	max.
Overall width with lead protrusion:60R110-60R300			58	
Lead protrusion	L₁	I₁	1.0	max.
Protrusion of cut out	L	L	11	max.
Protrusion beyond hold-down tape	I₂	I₂	Not specified	
Sprocket hole pitch:60R010-60R090	P₀	P₀	12.7	-/+ 0.3
Sprocket hole pitch:60R110-60R300	P₀	P₀	25.4	-/+ 0.5
Pitch tolerance			20 consecutive.	-/+ 1
Device pitch:60R010-60R090			12.7	
Device pitch:60R110-60R300			25.4	
Tape thickness	t	t	0.9	max.
Tape thickness with splice	t₁		2.0	max.
Splice sprocket hole alignment			0	-/+ 0.3
Body lateral deviation	Δh	Δh	0	-/+ 1.0
Body tape plane deviation	Δp	Δp	0	-/+ 1.3
Ordinate to adjacent component lead*:60R010-60R090	P₁	P₁	3.81	-/+ 0.7
Ordinate to adjacent component lead*:60R110-60R300			7.62	-/+ 0.7
Lead spacing:60R010-60R185	F	F	5.08	-/+ 0.8
Lead spacing:60R250-60R300	F	F	10.18	-/+ 0.8

*Differs from EIA Specification

Tape and Ammo Diagram



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Littelfuse:](#)

[060R0040XU](#) [60R110-PB](#) [60R300-PB](#) [060R0185U](#) [060R0110U](#) [060R0017U](#) [060R0375U](#) [060R0020U](#)
[060R0075U](#) [060R0065U](#) [060R0300U](#) [060R0160U](#) [060R0250U](#) [060R0135U](#) [060R0010U](#) [060R0050U](#) [060R0090U](#)